



LNP™ THERMOCOMP™ Compound DX11354

Asia Pacific: COMMERCIAL

This is a PC compound with good plating, surface and mechanical performance, a good candidate for Laser Direct Structuring applications.

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
MECHANICAL			
Tensile Stress, yld, Type I, 50 mm/min	600	kgf/cm ²	ASTM D 638
Tensile Stress, brk, Type I, 50 mm/min	530	kgf/cm ²	ASTM D 638
Tensile Strain, yld, Type I, 50 mm/min	5.7	%	ASTM D 638
Tensile Strain, brk, Type I, 50 mm/min	64	%	ASTM D 638
Tensile Modulus, 50 mm/min	26100	kgf/cm ²	ASTM D 638
Flexural Stress, yld, 1.3 mm/min, 50 mm span	920	kgf/cm ²	ASTM D 790
Flexural Stress, brk, 1.3 mm/min, 50 mm span	910	kgf/cm ²	ASTM D 790
Flexural Modulus, 1.3 mm/min, 50 mm span	23400	kgf/cm ²	ASTM D 790
IMPACT			
Izod Impact, notched, 23°C	76	cm-kgf/cm	ASTM D 256
THERMAL			
HDT, 1.82 MPa, 3.2mm, unannealed	124	°C	ASTM D 648
CTE, -40°C to 40°C, flow	6.3E-05	1/°C	ASTM E 831
CTE, -40°C to 40°C, xflow	6.9E-05	1/°C	ASTM E 831
PHYSICAL			
Density	1.27	g/cm ³	ASTM D 792
Moisture Absorption, 50% RH, 24 hrs	0.01	%	ASTM D 570
Mold Shrinkage, flow, 24 hrs (5)	0.6 - 0.65	%	ASTM D 955
Mold Shrinkage, xflow, 24 hrs (5)	0.6 - 0.65	%	ASTM D 955
Melt Flow Rate, 300°C/1.2 kgf	12	g/10 min	ASTM D 1238
ELECTRICAL			
Relative Permittivity, 1 GHz	2.92	-	IEC 60250
Dissipation Factor, 1 GHz	0.007	-	IEC 60250
FLAME CHARACTERISTICS			
UL Compliant, 94HB Flame Class Rating (3)(4)	0.6	mm	UL 94 by SABIC-IP



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PROCESSING PARAMETERS	TYPICAL VALUE	Unit
Injection Molding		
Drying Temperature	100 - 110	°C
Drying Time	3 - 4	hrs
Drying Time (Cumulative)	8	hrs
Maximum Moisture Content	0.02	%
Melt Temperature	275 - 300	°C
Nozzle Temperature	275 - 300	°C
Front - Zone 3 Temperature	260 - 300	°C
Middle - Zone 2 Temperature	255 - 295	°C
Rear - Zone 1 Temperature	250 - 290	°C
Hopper Temperature	60 - 80	°C
Mold Temperature	60 - 90	°C
Back Pressure	0.3 - 0.7	MPa
Screw Speed	40 - 70	rpm
Shot to Cylinder Size	30 - 80	%
Vent Depth	0.038 - 0.076	mm